

RD Number: RD135

RD Title: TB67H303HG Evaluation circuit

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	C_Vreg	1	0.1μF,25V	GRM319R72A104KA01D		Chip capacitor		
2	C_Vcc2	1	0.1μF,25V	GRM319R72A104KA01D		Chip capacitor		
3	C_Vref	1	0.1μF,25V	GRM319R72A104KA01D		Chip capacitor		
4	C_Vcc1	1	100μF,50V	GRM319R72A104KA01D		Electrolytic capacitor		
5	C_VDD	0	10μF,25V	EKMG500ELL101MHB5D		Electrolytic capacitor		✓
6	C_O1	0				Chip capacitor		✓
7	C_O2	0				Chip capacitor		✓
8	CON1	1		1760510000		Connector		
9	OUT1	1		ST-1-3	Mac8	Logic pin		
10	OUT2	1		ST-1-3	Mac8	Logic pin		
11	RRS	0		ST-1-3	Mac8	Logic pin		✓
12	Vreg	1		ST-1-3	Mac8	Logic pin		
13	VDD	1		ST-1-3	Mac8	Logic pin		
14	Vcc	1		ST-1-3	Mac8	Logic pin		
15	ALERT1	1		ST-1-3	Mac8	Logic pin		
16	SELECT	1		ST-1-3	Mac8	Logic pin		
17	Vref	1		ST-1-3	Mac8	Logic pin		
18	STBY	1		ST-1-3	Mac8	Logic pin		
19	IN1	1		ST-1-3	Mac8	Logic pin		
20	IN2	1		ST-1-3	Mac8	Logic pin		
21	PWM	1		ST-1-3	Mac8	Logic pin		
22	OSC	1		ST-1-3	Mac8	Logic pin		
23	ALERT2	1		ST-1-3	Mac8	Logic pin		
24	GND1	1		ST-1-3	Mac8	Logic pin		
25	GND2	1		ST-1-3	Mac8	Logic pin		
26	GND3	1		ST-1-3	Mac8	Logic pin		

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